

Amendments to the Claims:

Claims 1-18 **(Cancelled)**

19. **(New)** A transfer member comprising:

a substrate sheet;

a mold release layer laminated on said substrate sheet, said mold release layer being constituted by a plurality of elongated mold release belt portions separated from one another so that a space is defined between each adjacent pair of said mold release belt portions;

an ionizing radiation curing layer laminated all over said mold release layer, and all over said substrate sheet in areas not covered by said mold release layer;

a patterned layer laminated on said ionizing radiation curing layer; and

an adhesive layer laminated on said patterned layer in such a manner that said adhesive layer is located on said patterned layer only in areas that are superposed over said mold release belt portions of said mold release layer, such that said adhesive layer is not provided in areas not superposed over said mold release belt portions of said mold release layer.

20. **(New)** The transfer member of claim 19, wherein

said adhesive layer is laminated in areas that are respectively narrower than said mold release belt portions over which said adhesive layer is superposed.

21. **(New)** The transfer member of claim 19, further comprising

an anchor layer laminated between said ionizing radiation curing layer and said patterned layer.

22. **(New)** The transfer member of claim 21, wherein

said adhesive layer is laminated so as to be superposed over an entirety of each of said mold release belt portions of said mold release layer.

23. (New) The transfer member of claim 19, wherein

said adhesive layer is laminated so as to be superposed over an entirety of each of said mold release belt portions of said mold release layer.

24. (New) A transfer member arrangement comprising a resin board, and a transfer member bonded to said resin board, said transfer member comprising:

a substrate sheet;

a mold release layer laminated on said substrate sheet, said mold release layer being constituted by a plurality of elongated mold release belt portions separated from one another so that a space is defined between each adjacent pair of said mold release belt portions;

an ionizing radiation curing layer laminated all over said mold release layer, and all over said substrate sheet in areas not covered by said mold release layer;

a patterned layer laminated on said ionizing radiation curing layer; and

an adhesive layer laminated on said patterned layer in such a manner that said adhesive layer is located on said patterned layer only in areas that are superposed over said mold release belt portions of said mold release layer, such that said adhesive layer is not provided in areas not superposed over said mold release belt portions of said mold release layer;

wherein said transfer member has a peel strength smaller than 50 N/m with respect to said resin board in areas in which said mold release layer is not provided, when said substrate sheet is peeled off at an angle of 90° with respect to said resin board.

25. (New) The transfer member arrangement of claim 24, wherein

said adhesive layer is laminated in areas that are respectively narrower than said mold release belt portions over which said adhesive layer is superposed.

26. **(New)** The transfer member arrangement of claim 24, further comprising an anchor layer laminated between said ionizing radiation curing layer and said patterned layer.
27. **(New)** The transfer member arrangement of claim 26, wherein said adhesive layer is laminated so as to be superposed over an entirety of each of said mold release belt portions of said mold release layer.
28. **(New)** The transfer member arrangement of claim 24, wherein said adhesive layer is laminated so as to be superposed over an entirety of each of said mold release belt portions of said mold release layer.